

Low forward voltage TVS Transky™

Features

- High peak pulse power:
 - 600 W (10/1000 μ s)
 - 4000 W (8/20 μ s)
- Stand-off voltage 5 or 12 V
- Low forward voltage: 0.48 V @ 0.85 A @ 25 °C
- Low clamping factor V_{CL}/V_{BR}
- Fast response time
- Very thin package (1.0 mm overall component height)
- ECOPACK2® halogen-free package

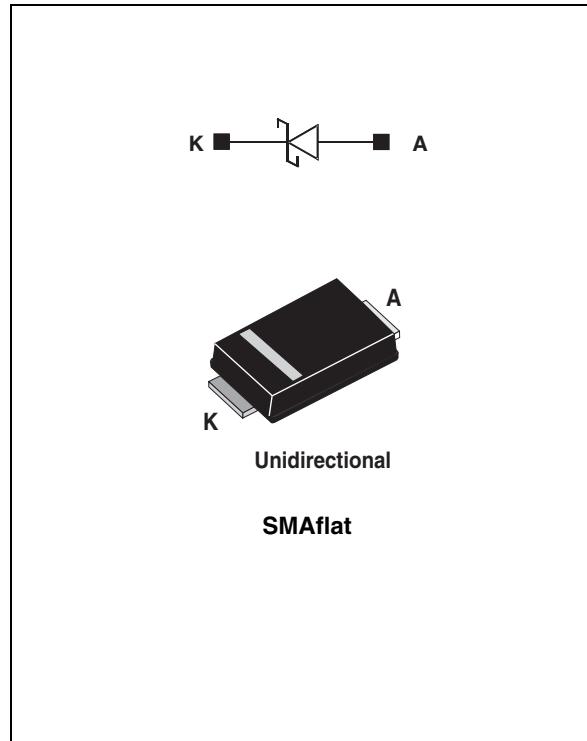
Complies with the following standards:

- IEC 61000-4-2 level 4:
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883E- Method 3015-7: class 3C
 - Human body model

Description

The Transky is designed specifically for portable equipment and miniaturized electronic devices subject to ESD transient overvoltages.

The Transky combines the performance of a Transil™ or TVS (transient voltage suppressor) and low forward voltage Schottky diode in a monolithic structure.



TM: Transky is a trademark of STMicroelectronics.

TM: Transil is a trademark of STMicroelectronics.

1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

| Symbol | Parameter | Value | Unit |
|-----------|---|--|-------------|
| V_{PP} | IEC 61000-4-2 standard | Air discharge Contact discharge | 15 8 |
| P_{PP} | Peak pulse power dissipation ⁽¹⁾ | T_j initial = T_{amb} | 600 |
| I_{FSM} | Non repetitive surge peak forward current | $t_p = 10$ ms $T_j = T_{initial} = T_{amb}$ | 25 |
| T_{stg} | Storage temperature range | | -65 to +175 |
| T_j | Operating junction temperature range | | -40 to +175 |

1. 10/1000 μ s pulse waveform

Table 2. Thermal resistance

| Symbol | Parameter | Value | Unit |
|---------------|-------------------|-------|------|
| $R_{th(j-l)}$ | Junction to leads | 20 | °C/W |

Table 3. Electrical characteristics - parameters ($T_{amb} = 25$ °C)

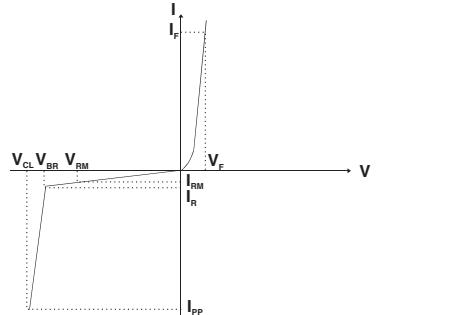
| Symbol | Parameter |  | |
|----------|----------------------------|--|--|
| V_{BR} | Breakdown voltage | | |
| I_{RM} | Leakage current @ V_{RM} | | |
| V_{RM} | Stand-off voltage | | |
| V_{CL} | Clamping voltage | | |
| R_d | Dynamic resistance | | |
| I_{PP} | Peak pulse current | | |
| C | Capacitance | | |

Table 4. Electrical characteristics - values ($T_{amb} = 25$ °C)

| Type | V_F max ($I_F = 0.85$ A) | I_{RM} max @ V_{RM} | | V_{BR} @ I_R ⁽¹⁾ | | | V_{CL} @ I_{PP} 10/1000 μ s | | R_d ⁽²⁾ 10/1000 μ s | | V_{CL} @ I_{PP} 8/20 μ s | | R_d ⁽²⁾ 8/20 μ s | | αT ⁽³⁾ |
|-----------|--------------------------------|-------------------------|-------|---------------------------------|------|------|--|----------|---|----|-------------------------------------|------|--------------------------------------|-------|---------------------------|
| | | 25 °C | 85 °C | min | typ | max | max | | max | | max | | max | max | max |
| | V | μ A (max) | V | V | mA | V | A | Ω | V | A | Ω | | 10-4/°C | | |
| SMTYF5.0A | 0.48 | 10 | 500 | 5 | 6.40 | 6.74 | 7.07 | 10 | 9.2 | 68 | 0.029 | 13.4 | 298 | 0.021 | 5.7 |
| SMTYF12A | 0.48 | 20 | 1200 | 12 | 13.2 | 13.7 | 14.3 | 1 | 18.5 | 31 | 0.129 | 22.9 | 157 | 0.055 | 7.8 |

1. Pulse test: $t_p < 50$ ms.

2. To calculate maximum clamping voltage at other surge currents, use the following formula
 $V_{CLmax} = R_d \times I_{PP} + V_{BRmax}$

3. To calculate V_{BR} versus junction temperature, use the following formula:

$$V_{BR} @ T_j = V_{BR} @ 25 \text{ °C} \times (1 + \alpha T \times (T_j - 25))$$

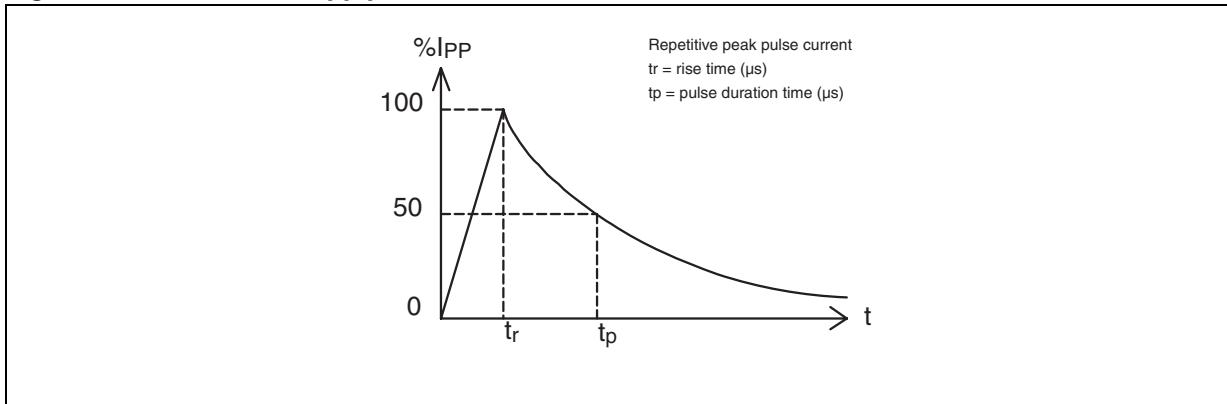
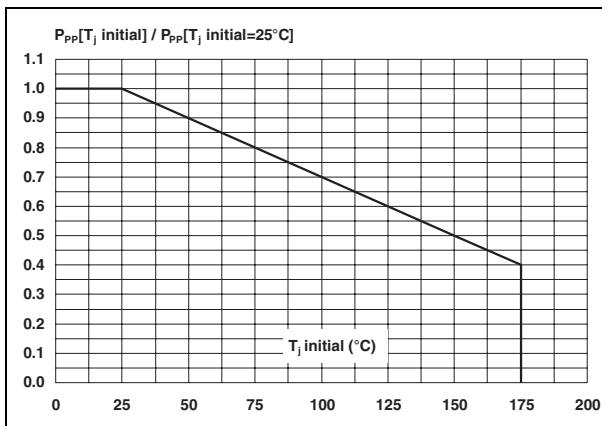
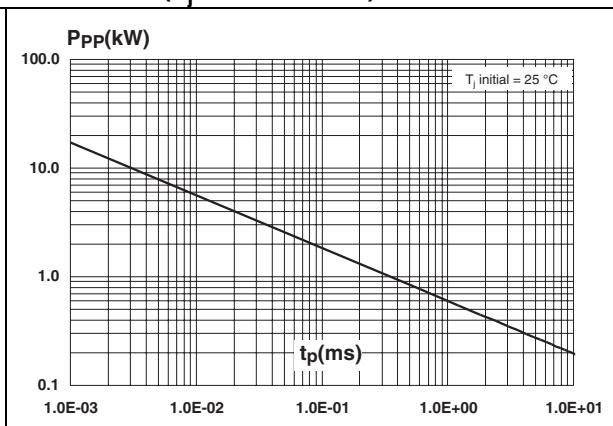
Figure 1. Definition of I_{PP} pulse**Figure 2. Relative peak power dissipation versus initial junction temperature****Figure 3. Peak pulse power versus exponential pulse duration (Tj initial = 25 °C)**

Figure 4. Clamping voltage versus peak pulse current (exponential waveform, maximum values)

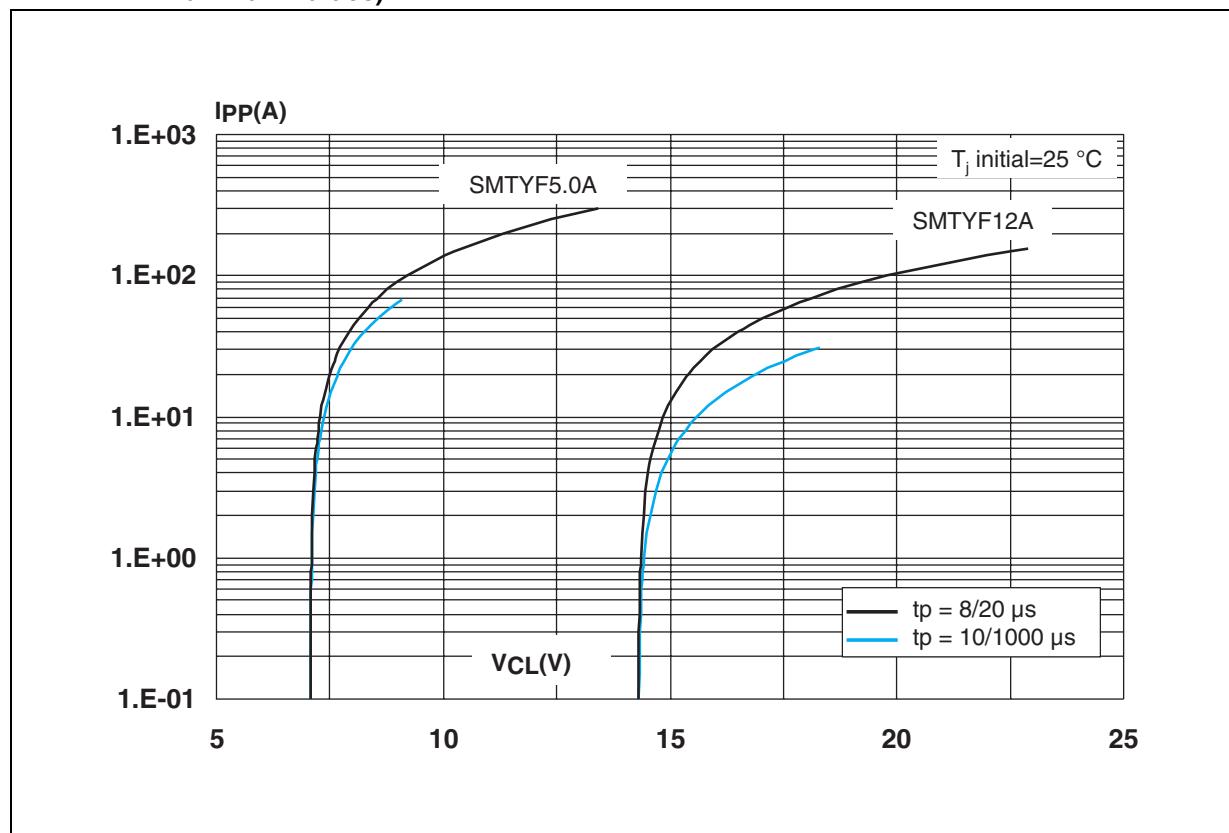


Figure 5. Junction capacitance versus reverse applied voltage (typical values)

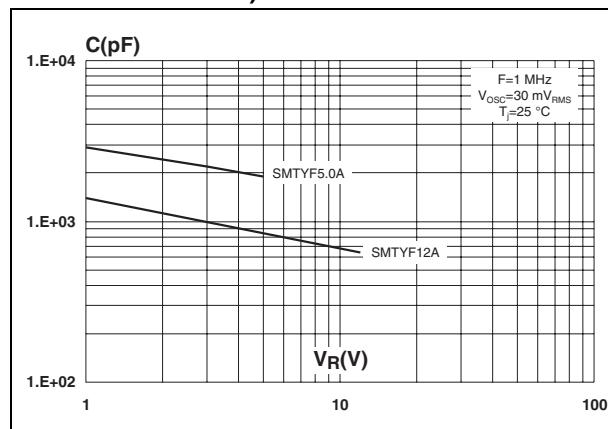


Figure 6. Forward voltage drop versus forward current (typical values)

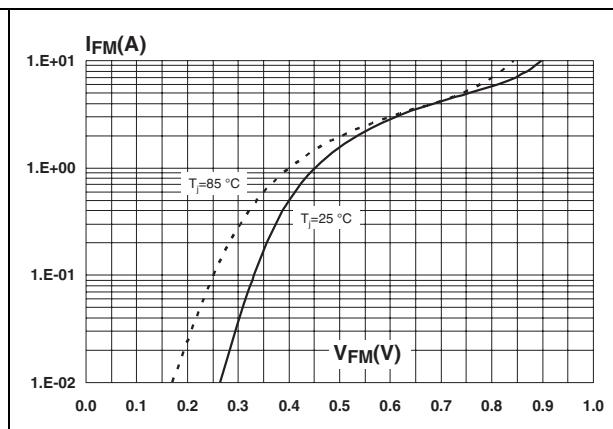


Figure 7. Average power dissipation versus ambient temperature

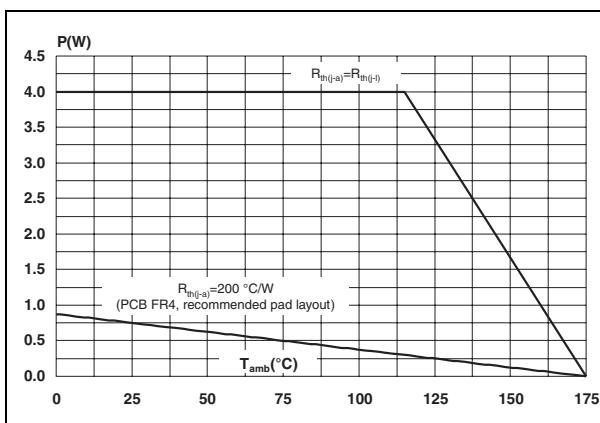


Figure 9. Thermal resistance junction to ambient versus copper surface under each lead (printed circuit board FR4, copper thickness = 35 μ m)

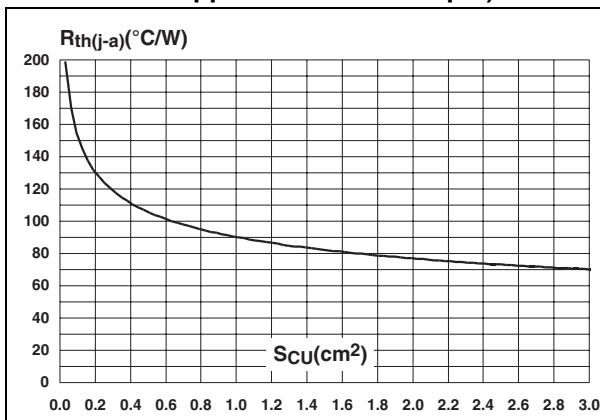


Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration (printed circuit board FR4, $S_{Cu} = 1 \text{ cm}^2$)

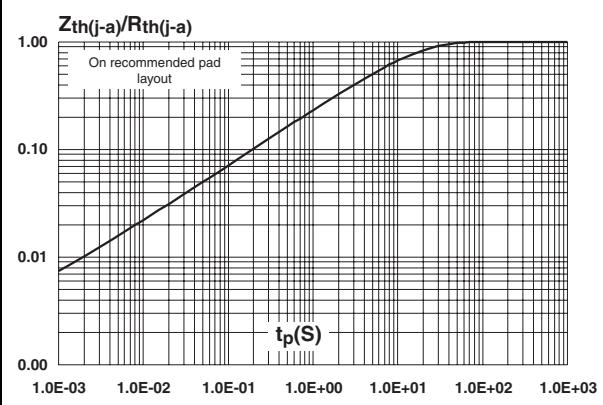
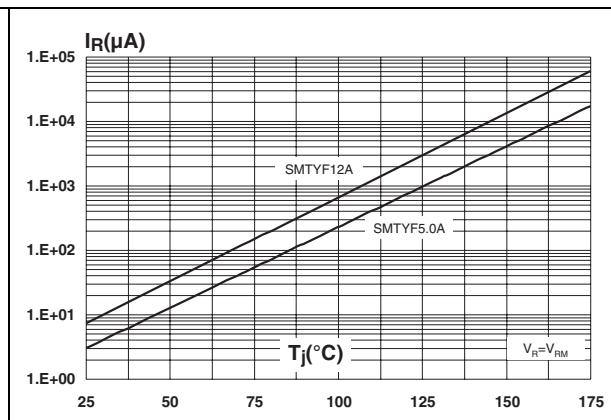


Figure 10. Leakage current versus junction temperature (typical values)



2 Package information

- Case: JEDEC DO-221AC molded plastic over Planar junction
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Band indicates cathode
- Flammability: Epoxy rated UL94V-0
- RoHS package

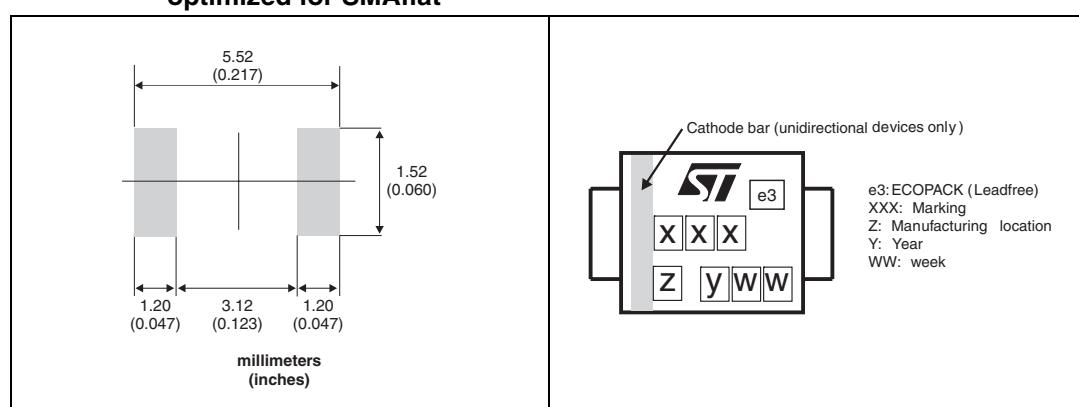
In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at www.st.com.

Table 5. SMAflat dimensions

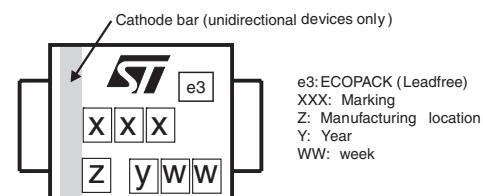
| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 0.90 | | 1.10 | 0.035 | | 0.043 |
| b | 1.25 | | 1.65 | 0.049 | | 0.065 |
| c | 0.15 | | 0.40 | 0.006 | | 0.016 |
| D | 2.25 | | 2.95 | 0.088 | | 0.116 |
| E | 4.80 | | 5.60 | 0.189 | | 0.220 |
| E1 | 3.95 | | 4.60 | 0.156 | | 0.181 |
| L | 0.75 | | 1.50 | 0.030 | | 0.059 |
| L1 | | 0.50 | | | 0.019 | |
| L2 | | 0.50 | | | 0.019 | |

Figure 11. SMAflat footprint dimensions

optimized for SMAflat⁽¹⁾



1. SMA footprint may also be used.



e3: ECOPACK (Leadfree)
 XXX: Marking
 Z: Manufacturing location
 Y: Year
 WW: week

3 Ordering information

Table 6. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|------------|---------|---------|---------|----------|---------------|
| SMTYF5.0A | YF5.0 | SMAflat | 0.035 g | 10 000 | Tape and reel |
| SMTYF12A | YF12 | | | | |

4 Revision history

Table 7. Document revision history

| Date | Revision | Description of changes |
|-------------|----------|------------------------|
| 04-Sep-2008 | 1 | First issue |

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